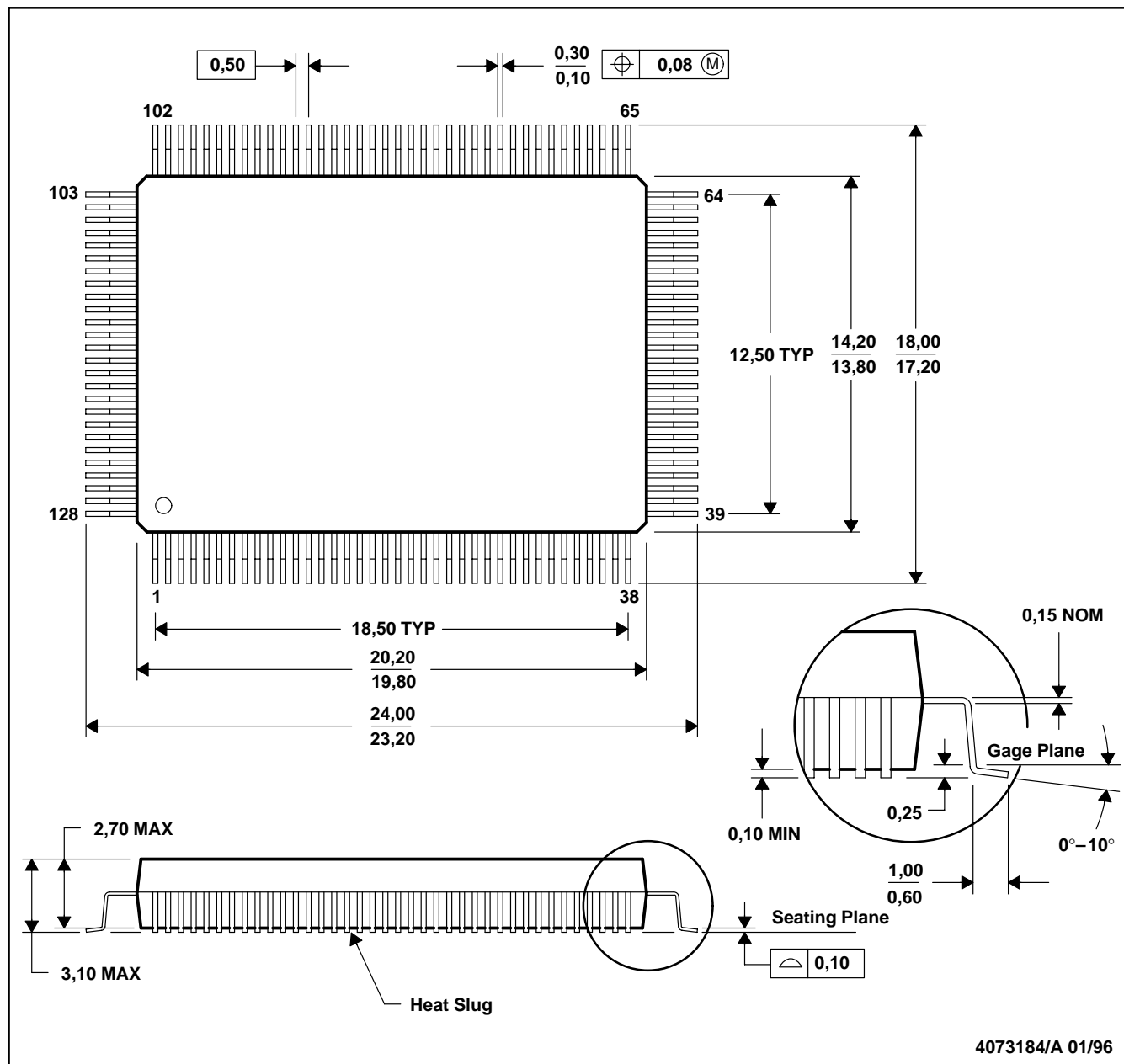


PDL (R-PQFP-G128)

PLASTIC QUAD FLATPACK



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Thermally enhanced molded plastic package with a heat slug (HSL)

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